CHOMERICS

- Phase-change thermal interface materials
- Thermally conductive adhesive tapes
- Thermally conductive insulator pads
- Thermally conductive gap fillers
- Thermally conductive silicone compounds

• Flexible heat spreaders • Thermal management for BGAs

Parker Seals

LEADER IN THERMAL MANAGEMENT: DESIGN, INNOVATION AND MATERIALS

CHO-THERM® T500 Highly Thermally Conductive Elastomer Insulators

MATERIAL DESCRIPTION & PRODUCT FORM OPTIONS

CHO-THERM T500 material is a highly thermally conductive interface insulator designed for use where the lowest possible thermal impedance is required.

One-component CHO-THERM T500 insulators combine a silicone binder with a boron nitride filler to deliver thermal impedance of just 0.19°C-in²/watt.

This elastomer is designed for use at temperatures ranging from -60°C to 200°C.

Fiberglass cloth reinforcement strengthens CHO-THERM T500 pads against tear, cut-through and punctures. The material is available in sheet form and die-cut configurations. An optional pressure-sensitive adhesive is available on one side.

In contrast to conventional insulators with thermal grease, CHO-THERM T500 material does not crack, tear or otherwise fail when torqued between mating metal surfaces. CHO-THERM T500 material eliminates the problems associated with silicone migration, contamination or drying out.

CRITICAL PERFORMANCE CHARACTERISTICS

There are generally two objectives that must be satisfied in the interface:

- 1. To enhance the flow of heat from the device to the heat sink.
- 2. To provide electrical isolation.

CHO-THERM T500 material performs both functions simultaneously, effectively replacing combinations of beryllium oxide or mica wafers and silicone grease.

	TYPICAL PROPERTIES	T500	TEST METHOD
CONSTRUCTION	Binder	Silicone	_
	Filler	Boron Nitride	_
	Carrier	Fiberglass	_
	Color	Green	Visual
	Thickness, inch (mm)	0.010 (0.25)	ASTM D374
THERMAL	Thermal Impedance, °C-in²/W (°C-cm²/W)	0.19 (1.23)	ASTM D5470
	Thermal Conductivity, W/m-K	2.07	ASTM D5470
	Operating Temperature Range, °C	-60 to +200	_
ELEC.	Voltage Breakdown, Vac	5000	ASTM D149
	Volume Resistivity, ohm-cm	1 x 10 ¹⁴	ASTM D257
MECHANICAL	Tensile Strength, psi (MPa)	1000 (6.89)	ASTM D412
	Tear Strength, Ib/in (kN/m)	100 (17.5)	ASTM D624
	Elongation, %	10	ASTM D412
	Hardness (Shore A)	82	ASTM D2240
	Specific Gravity	1.55	ASTM D792
	UL Recognized	File No. 57104	QMFZ2
	Outgassing: % TML % CVCM	0.40 0.10	ASTM E595

TML= Total Mass Loss

CVCM= Collected Volatile Condensible Materials

Note: Pressure-sensitive adhesive may increase thermal impedance by as much as 0.05°C-in²/W (0.32°C-cm²/W). Contact Chomerics for further information.

CONTACT PRESSURE & MOUNTING TORQUE

The optimum contact pressure range for CHO-THERM materials is 300-500 psi $(2.07 \times 10^6 - 3.45 \times 10^6 \text{N/m}^2)$. Beyond this range, thermal performance gains are negligible.

To convert mounting torque into contact pressure, use the following equation:

$$\mathsf{P} = \frac{(\mathsf{T})(\mathsf{N})}{(0.2)(\mathsf{D})(\mathsf{A})}$$

- P = Contact Pressure (psi or N/m²)
- T = Torque (in-lbs or N-m)
- N = Number of Fasteners
- (0.2) = Average Friction Factor
 - D = Diameter (in. or m)
 - A = Contact Area (in² or m²)

IMPROVEMENT IN THERMAL IMPEDANCE WITH TIME

The thermal impedance characteristics of CHO-THERM materials can be expected to improve during use due to stress relaxation of the elastomer and consequent additional filling of the microscopic voids in the interface. Improvement can be as much as 10-15% after the first few weeks of use.

TECHNICAL

BULLETIN

continued

THERMAL INTERFACE IMPEDANCE

The thermal performance of interface materials is generally characterized by the thermal impedance across the interface in °C-in²/watt. The lower the value of thermal interface impedance, the better the thermal performance.

The thermal impedance of an interface depends greatly on a number of different parameters, including the flatness and smoothness of the mating surfaces forming the interface and the contact pressure between them, as well as the thickness of the interface material, its thermal conductivity and conformability.

VOLTAGE BREAKDOWN CHARACTERISTICS

When using thermal interface pads to electrically isolate a component from a metal heat sink or chassis, the critical material property for the pad is its dielectric strength. Dielectric strength is a measure of how well a material can prevent the voltage on the component case from arcing through the material and allowing an electrical short circuit between the component and the metal mounting surface. This property is commonly presented as the voltage breakdown shown in the Typical Properties Table, and is determined by electrical testing of multiple flat sheet samples in accordance with the test procedures detailed in ASTM D149. The higher the value of voltage breakdown, the better

the material is at withstanding applied voltages.

The dielectric strength of a material can also be affected by many external factors including: insulator thickness, area of the contact surfaces, temperature, humidity, mechanical stress applied to the insulator, the presence of partial discharge, etc. Contact Chomerics Applications Engineering for details of test methods and assistance with the electrical requirements of your specific application.

CHEMICAL & SOLVENT RESISTANCE

Exposure to petrochemicals or chlorinated solvents, such as trichlorethylene, freon, toluene, trichlorethane and other cleaning agents, chemicals and solvents used in vapor degreasing, defluxing and cleaning operations is not harmful to CHO-THERM T500 materials, although exposed edges do tend to swell. The amount of swelling is a function of exposure time and type of solvent. After drying out, the exposed edges will return to their former size and conditions with no effect on thermal or electrical properties. CHO-THERM T500 material is recognized under the Components Program of Underwriters Laboratories, Inc.

ORDERING INFORMATION

Using the diagram below, construct the appropriate part number. Part numbers for non-standard configurations will be assigned by Chomerics

For customized die-cut parts, submit a detailed drawing of the desired part, including all dimensions, tolerances, hole locations and profile. When specifying pressure-sensitive adhesive (PSA) on non-symmetrical die-cut parts, indicate to which side PSA is to be applied.

All CHO-THERM products are available through local Chomerics distributors. Contact Chomerics for the distributor in your area.





NOTICE: The information contained herein is to the best of our knowledge true and accurate. However, since the varied conditions of potential use are beyond our control, all recommendations or suggestions are presented without guarantee or responsibility on our part and users should make their own tests to determine the suitability of our products in any specific situation. This product is sold without warranty either expressed or implied, of fitness for a particular purpose or otherwise, except that this product shall be of standard quality, and except to the extent otherwise stated on Chomerics' invoice, quotation, or order acknowledgement. We disclaim any and all liability incurred in connection with the use of information contained herein, or otherwise. All risks of such are assumed by the user. Furthermore, nothing contained herein shall be construed as a recommendation to use any product or material or its use.

